

Abstract of the Disclosure

The method and apparatus of the present invention dissipate heat from an electronic device to provide an efficient and universally applied thermal solution for high heat generating electronic devices. The apparatus comprises an evaporator, a condenser, a heater and conduits. The evaporator, condenser, and conduits define a closed system that has an interior volume which is partially filled with a liquid coolant. The evaporator is thermally connected to an electronic device, such as a processor, and removes thermal energy from the processor by evaporating the liquid coolant. When the apparatus is oriented such that no liquid coolant is in contact with the evaporator, the heater applies thermal energy to the coolant until the coolant begins to boil. Boiling the liquid coolant causes bubbles to form within the liquid coolant. The volume of the bubbles generated by boiling raises the level of the liquid coolant within the closed system until the liquid coolant comes into contact with the evaporator. The evaporator is then able to evaporate the liquid coolant and remove thermal energy from the processor.

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